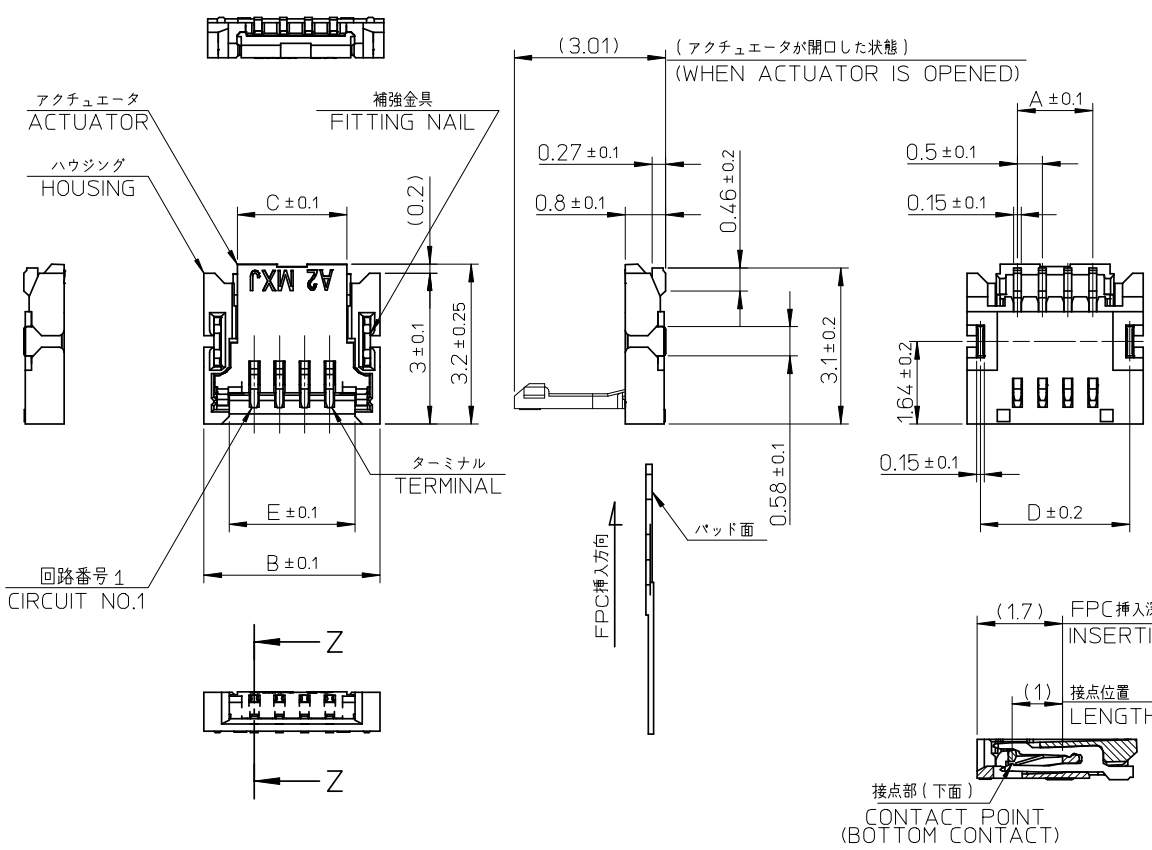


注記
NOTES:

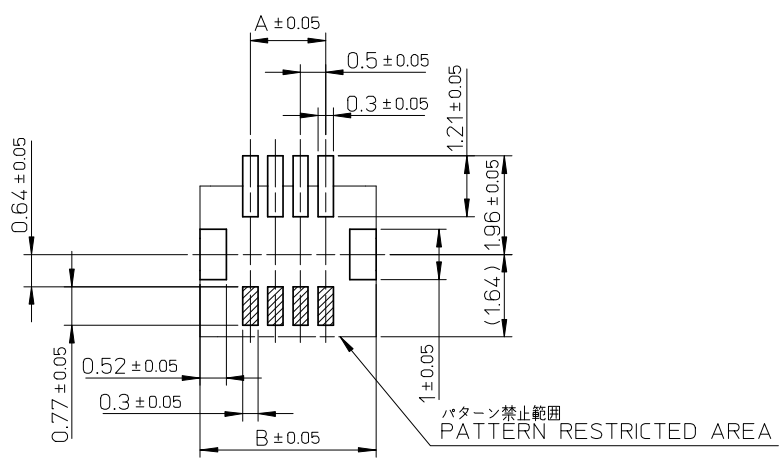
- 材質
MATERIAL
ハウジング: ポリアミド46、ガラス充填、UL94HB 塩素系、臭素系難燃材 非使用
HOUSING: PA46, GLASS FILLED, UL94HB
CHLORINATED FLAME RETARDANTS FREE/
BROMINATED FLAME RETARDANTS FREE.
アクチュエーター: ポリアミド46、ガラス充填、UL94HB 塩素系、臭素系難燃材 非使用
ACTUATOR: PA46, GLASS FILLED, UL94HB
CHLORINATED FLAME RETARDANTS FREE/
BROMINATED FLAME RETARDANTS FREE.
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
補強金具: 銅合金 (t=0.15)
NAIL: COPPER ALLOY (t=0.15)
- めっき仕様
PLATING
ターミナル: 部分金メッキ
接点部 0.1マイクロメートル以上
半田付け部 0.05マイクロメートル以上
TERMINAL: SEPARATED GOLD PLATING
CONTACT AREA 0.1 MICROMETER MINIMUM.
SOLDER TAIL AREA 0.05 MICROMETER MINIMUM.
下地 ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING; NICKEL PLATING 1.0 MICROMETER MINIMUM.
補強金具: 錫メッキ 1.0マイクロメートル以上
NAIL: TIN PLATING 1.0 MICROMETER MINIMUM.
下地 ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING; NICKEL PLATING 1.0 MICROMETER MINIMUM.
- 平坦度は、0.1mm以下とする。
TAILS AND NAILS COPLANARITY TO BE 0.1mm MAXIMUM.



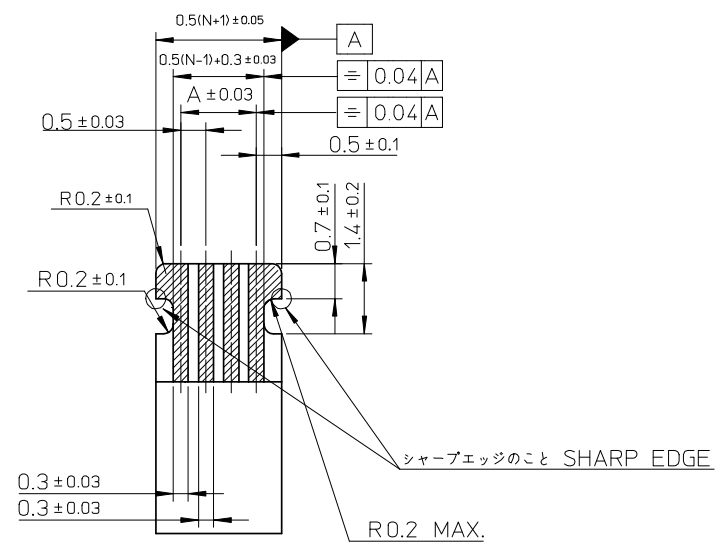
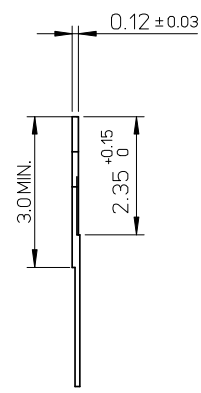
SECTION Z-Z (ACTUATOR CLOSED)

2.5	2.97	2.18	3.5	1.5	503043-0401	503043-0409	4
E	D	C	B	A	エンボス梱包品 製品番号		極数(N)
EMBOSSED PACKAGING MATERIAL NO. CIRCUITS(N)							

REVISED EC NO: J2009-0418 DRWN: ASUZUKI 2008/08/19 CHKD: HMATSUMOTO 2008/08/19 APPR: NUKITA 2008/08/20	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY Y. AOYAGI	DATE 2008/02/26	TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY			
		10 OVER 30 UNDER	±0.25	CHECKED BY E. SATO	DATE 2008/02/26	MOLEX INCORPORATED			
		30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2008/02/26	DOCUMENT NO. SD-503043-001			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR ±1°		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	



推奨基板寸法
RECOMMENDED P.C. BOARD PATTERN LAYOUT



推奨FPC寸法
RECOMMENDED FPC PATTERN LAYOUT

FPCについて:
 抜き方向は、導体側から補強板側を推奨します。
 補強フィルム材質は、ポリイミドを推奨します。
 接着剤は、熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は、導通不良の原因となりますので染み出しが無いよう、お願いします。

ABOUT FPC:
 RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
 RECOMMENDED MATERIAL:
 STIFFNER FILM: POLYIMIDE
 BONDING AGENT: THERMOSETTING AGENT
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE MAY CAUSE
 THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2009-0418 DRW:NASUZUKI01 2008/08/19 CHKD:HMATSUMOTO 2008/08/19 APPR:NUKITA 2008/08/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY Y. AOYAGI	DATE 2008/02/26	TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY	
	10 OVER 30 UNDER	± 0.25	CHECKED BY E. SATO	DATE 2008/02/26	MOLEX INCORPORATED	
	30 OVER	± 0.3	APPROVED BY N. UKITA	DATE 2008/02/26	DOCUMENT NO. SD-503043-001	SHEET NO. 2 OF 2
A	ANGULAR ± 1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		